

#### 1 Characteristics

Table 1. Absolute Ratings (limiting values at 25 °C, unless otherwise specified, anode terminals short circuited)

Symbol	Parameter	Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage			V
I <sub>F(RMS)</sub>	Forward rms current	45	Α	
I <sub>F(AV)</sub>	Average forward current, δ = 0.5, square wave	30	Α	
I <sub>FSM</sub>	Surge non repetitive forward current	200	Α	
P <sub>ARM</sub>	Repetitive peak avalanche power	900	W	
T <sub>stg</sub>	Storage temperature range	-65 to +175	°C	
Tj	Maximum operating junction temperature <sup>(1)</sup>	150	°C	

<sup>1.</sup>  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameters

Symbol	Parameter	Max. value	Unit
R <sub>th(j-c)</sub>	Junction to case	2.5	°C/W

For more information, please refer to the following application note:

• AN5046 : Printed circuit board assembly recommendations for STMicroelectronics PowerFLAT™ packages

Table 3. Static electrical characteristics (anode terminals short circuited)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>	-		15	μA
IR V		T <sub>j</sub> = 125 °C		-	4	12	mA
	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 15 A	-		0.88	V
V <sub>F</sub> <sup>(2)</sup>		T <sub>j</sub> = 125 °C		-	0.65	0.70	
VF (=)		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 30 A			0.95	
		T <sub>j</sub> = 125 °C	1F = 30 A		0.71	0.79	

- 1. Pulse test:  $t_p$  = 5 ms,  $\delta$  < 2%
- 2. Pulse test:  $t_p$  = 380  $\mu$ s,  $\delta$  < 2%

To evaluate the conduction losses use the following equation:

 $P = 0.65 \times I_{F(AV)} + 0.0046 I_{F}^{2} (RMS)$ 

For more information, please refer to the following application notes related to the power losses:

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

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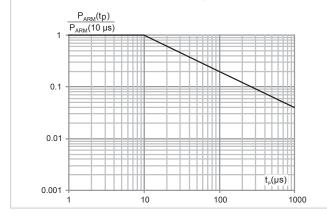


#### 1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current  $P_{F(AV)}(W)$ 32 δ= 0.5 28 δ= 0.2 24 δ= -δ= 0.1 20 δ = 0.05 16 12 8  $I_{F(AV)}(A)$ 0 0 10 15 25 35 40 30

Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ )  $I_{F(AV)}(A)$ 35  $R_{th(j-a)} = R_{th(j-c)}$ 30 25 20 15 10 Tamb(°C) 0 50 75 100 125 0 150

Figure 3. Normalized avalanche power derating versus pulse duration (T<sub>j</sub>= 125 °C)



to case versus pulse duration

Zth(j-c)/Rth(j-c)

0.9

0.8

0.7

Figure 4. Relative variation of thermal impedance junction

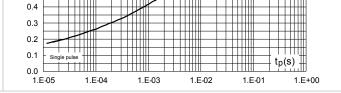


Figure 5. Reverse leakage current versus reverse voltage applied (typical values)

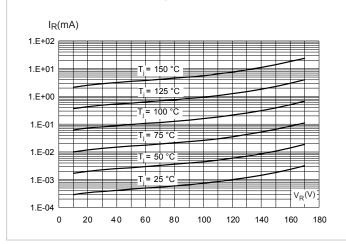
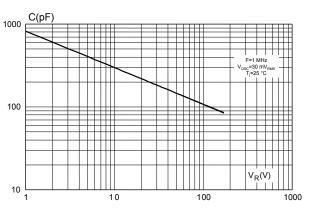


Figure 6. Junction capacitance versus reverse voltage applied (typical values)



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0.6



Figure 7. Forward voltage drop versus forward current

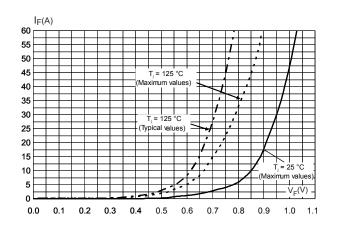
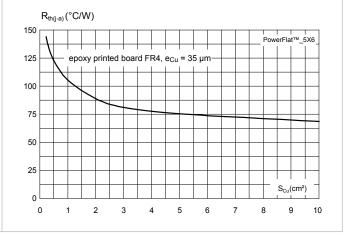


Figure 8. Thermal resistance junction to ambient versus copper surface under tab





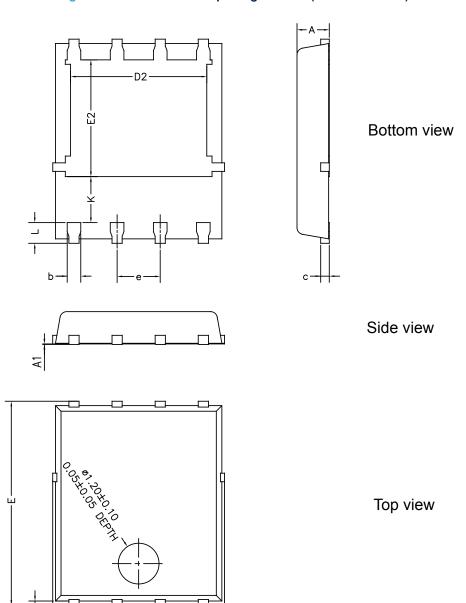
# 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

### 2.1 PowerFLAT™ 5x6 package information

- Epoxy meets UL 94,V0
- Cooling method: by conduction (C)

Figure 9. PowerFLAT™ 5x6 package outline (non-contractual)



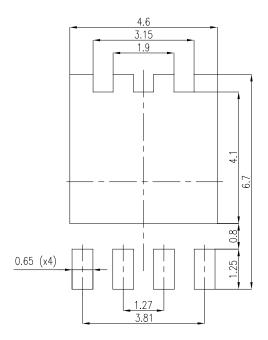
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Table 4. PowerFLAT™ 5x6 mechanical data

Dimensions							
Ref		Millimeters			Inches (for reference only)		
Kei	Min.	Тур.	Max.	Min.	Тур.	Max.	
А	0.80		1.00	0.031		0.039	
A1	0.00		0.05	0.000		0.002	
b	0.30		0.50	0.01		0.02	
С		0.25			0.010		
D	4.80		5.40	0.189		0.212	
D2	3.91		4.45	0.154		0.175	
е		1.27			0.050		
E	5.90		6.35	0.232		0.250	
E2	3.34		3.70	0.138		0.146	
L	0.50		0.80	0.020		0.031	
K	1.10		1.575	0.015		0.023	
L1	0.05	0.15	0.25	0.002	0.006	0.009	

Figure 10. PowerFLAT™ 5x6 recommended footprint (dimensions are in mm)



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# 3 Ordering information

**Table 5. Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS30170DJF-TR	PS30 170	PowerFLAT 5x6	0.095 g	3000	Tape and reel

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# **Revision history**

**Table 6. Document revision history** 

Date	Revision	Changes
06-Nov-2009	1	First issue.
30-Jul-2010	2	Updated Table 1.
20-May-2011	3	Corrected order code and marking in Table 6.
05-Jun-2018	4	Updated Table 1. Absolute Ratings (limiting values at 25 °C, unless otherwise specified, anode terminals short circuited) and Figure 3. Normalized avalanche power derating versus pulse duration ( $T_j$ = 125 °C). Minor text changes to improve readability.
08-Feb-2019	5	Updated Section Cover image, Figure 9. PowerFLAT™ 5x6 package outline (non-contractual) and Table 4. PowerFLAT™ 5x6 mechanical data.



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